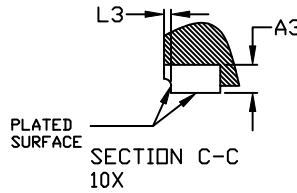
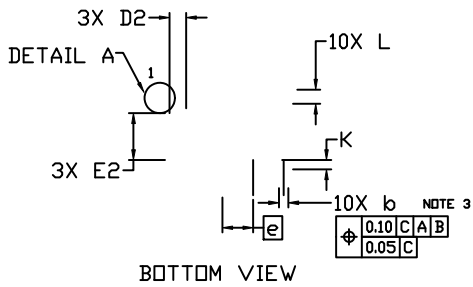
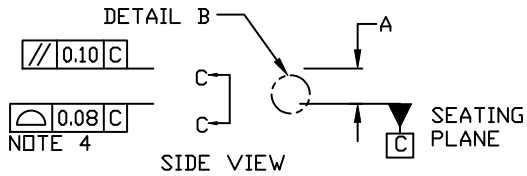
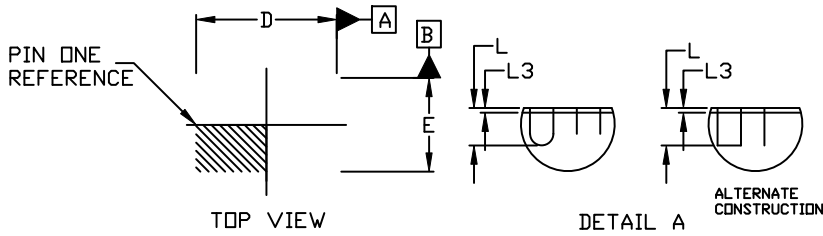


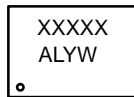
WDFNW10 3.0x2.0, 0.65P
CASE 515AL
ISSUE B

DATE 05 FEB 2020



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	---	0.05
A3	0.20 REF		
A4	0.10	---	---
b	0.15	0.20	0.25
D	2.90	3.00	3.10
D2	0.25	0.35	0.45
E	1.90	2.00	2.10
E2	0.90	1.00	1.10
e	0.65 BSC		
e2	0.60 BSC		
e3	0.95 BSC		
K	0.20 REF		
L	0.25	0.30	0.35
L3	---	---	0.09

GENERIC
MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb iFree Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb iFree indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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RECOMMENDED
MOUNTING FOOTPRINT